

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT8308092

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST IN PATENT COLLATERAL AT REEL/FRAME NO. 64185/0755
CONVEYING PARTY DATA	
Name	Execution Date
U.S. BANK TRUST COMPANY, NATIONAL ASSOCIATION, AS COLLATERAL AGENT	12/01/2023
RECEIVING PARTY DATA	
Name:	WOLFSPEED, INC.
Street Address:	4600 SILICON DRIVE
City:	DURHAM
State/Country:	NORTH CAROLINA
Postal Code:	27703
PROPERTY NUMBERS Total: 21	
Property Type	Number
Patent Number:	7170111
Patent Number:	7253454
Patent Number:	7615774
Patent Number:	7368971
Patent Number:	7612390
Patent Number:	9035354
Patent Number:	9373577
Patent Number:	9629246
Patent Number:	10615273
Patent Number:	10141303
Patent Number:	10483352
Patent Number:	10651168
Patent Number:	11417746
Patent Number:	10748996
Application Number:	17018721
Application Number:	17097294
Application Number:	17228978
Application Number:	17834421
Application Number:	17900652

Property Type	Number
Application Number:	17951711
Application Number:	18061246

CORRESPONDENCE DATA

Fax Number: (213)891-8763

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	056057-0019
NAME OF SUBMITTER:	RHONDA DELEON
SIGNATURE:	/Rhonda DeLeon/
DATE SIGNED:	12/04/2023

Total Attachments: 5

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RELEASE OF SECURITY INTEREST IN PATENT COLLATERAL

This RELEASE OF SECURITY INTEREST IN PATENT COLLATERAL, dated as of December 1, 2023 (this “Release”), is made by U.S. BANK TRUST COMPANY, NATIONAL ASSOCIATION, as collateral agent (together with its successors and assigns in such capacity, the “Collateral Agent”) for the Secured Parties (as defined in the Collateral Agreement) in favor of WOLFSPEED, INC., a North Carolina corporation (the “Pledgor”). Unless otherwise defined herein, capitalized terms used herein and not defined have the meaning given to them in the Collateral Agreement, or if not defined therein, the Agreement.

WITNESSETH

WHEREAS, the Pledgor, the other parties party thereto from time to time, and Collateral Agent entered into that certain Collateral Agreement, dated as of June 23, 2023 (as amended, restated, supplemented or otherwise modified from time to time, the “Collateral Agreement”);

WHEREAS, pursuant to the Collateral Agreement, the Pledgor and the Collateral Agent entered into that certain Notice of Grant of Security Interest in Intellectual Property, dated as of June 23, 2023 (the “Agreement”) and recorded with the U.S. Patent and Trademark Office (“USPTO”) on June 30, 2023 at Reel/Frame Nos. 64185/0755 through 64185/0823, pursuant to which the Pledgor granted to the Collateral Agent, its successors and permitted assigns, for the benefit of the Secured Parties, a security interest in all right, title and interest in or to the IP Collateral (as defined in the Agreement).

WHEREAS, the Pledgor has requested and the Collateral Agent has agreed to release its security interest in all of the right, title and interest in and to the issued patents and patent applications set forth in Schedule 1, attached hereto and incorporated herein by this reference (the “Released Collateral”), and to reconvey any and all of its right, title, and interest in and to the Released Collateral to the Pledgor; and

WHEREAS, the security interest in the remaining IP Collateral granted to the Collateral Agent pursuant to the Agreement (the “Remaining Collateral”), will be unaffected by this Release and such security interest in the Remaining Collateral will continue in full force and effect.

NOW, THEREFORE, in consideration of the foregoing, the Collateral Agent hereby TERMINATES, without recourse, representation, or warranty of any kind or nature the security interest in the Released Collateral, RELEASES and forever discharges, without recourse, representation, or warranty of any kind or nature its security interest in the Released Collateral, and retransfers and reassigns to the Pledgor any right, title or interest the Collateral Agent may have in, to or under the Released Collateral, without recourse, representation or warranty. The Collateral Agent shall retain its security interest in all other portions of the IP Collateral that are not the Released Collateral that is the subject of this Release.

Section 1. Recordation. The Collateral Agent authorizes the Pledgor (and its counsel or designee and any successor in interest to the Pledgor with respect to the Released Collateral) to record this Release with the USPTO.

Section 2. Signatures. Signatures delivered by facsimile transmission or other electronic means (e.g., PDF) shall be binding for all purposes hereof.

Section 3. Governing Law. This Release shall be construed in accordance with and governed by the laws of the state of New York, without regard to any principle of conflicts of law that could require application of any other law.

[SIGNATURE PAGE FOLLOWS]

IN WITNESS WHEREOF, the Collateral Agent has caused this Release to be duly executed and delivered as of the date first written above.

**U.S. BANK TRUST COMPANY, NATIONAL
ASSOCIATION,**
as Collateral Agent

By: 
Name: Ryan R. [unclear]
Title: Duly Authorized Signatory

[Signature Page to Release of Security Interest in Patent Collateral]

PATENT
REEL: 065758 FRAME: 0629

SCHEDULE I
to
RELEASE OF SECURITY INTEREST IN PATENT COLLATERAL

Patents

Title	Application No. Application Date	(Publication No.) Patent No. Issue Date
Nitride Heterojunction Transistors Having Charge-Transfer Induced Energy Barriers and Methods of Fabricating the Same	10/772,882 05-Feb-2004	7170111 30-Jan-2007
High Electron Mobility Transistor	11/073,484 03-Mar-2005	7253454 07-Aug-2007
Aluminum Free Group III-Nitride Based High Electron Mobility Transistors	11/118,575 29-Apr-2005	7615774 10-Nov-2009
High Power, High Frequency Switch Circuits Using Strings of Power Transistors	11/295,060 06-Dec-2005	7368971 06-May-2008
Heterojunction Transistors Including Energy Barriers and Related Method	11/357,752 17-Feb-2006	7612390 03-Nov-2009
Heterojunction Transistors Having Barrier Layer Bandgaps Greater than Channel Layer Bandgaps and Related Methods	12/566,973 25-Sep-2009	9035354 19-May-2015
Hybrid Semiconductor Package	13/899,048 21-May-2013	9373577 21-Jun-2016
PCB Based Semiconductor Package Having Integrated Electrical Functionality	14/811,325 28-Jul-2015	9629246 18-Apr-2017
Semiconductor Devices Having a Plurality of Unit Cell Transistors that Have Smoothed Turn-on Behavior and Improved Linearity	15/628,932 21-Jun-2017	10615273 07-Apr-2020
RF Amplifier Package with Biasing Strip	15/709,532 20-Sep-2017	10141303 27-Nov-2018
High Power Transistor with Interior-Fed Gate Fingers	16/032,571 11-Jul-2018	10483352 19-Nov-2019
RF Amplifier Package with Biasing Strip	16/135,163 19-Sep-2018	10651168 12-May-2020
High Power Transistor with Interior-Fed Fingers	16/393,280 24-Apr-2019	11417746 16-Aug-2022
High Power Transistor with Interior-Fed Gate Fingers	16/596,240 08-Oct-2019	10748996 18-Aug-2020
Packaging for RF Transistor Amplifiers	17/018,721 11-Sep-2020	(2022/0084950)
Packaged RF Power Device with PCB Routing	17/097,294 13-Nov-2020	(2022/0157671)
Multi-Die Package Having Different Types of Semiconductor Dies Attached to the Same Thermally Conductive Flange	17/228,978 13-Apr-2021	(2021/0233877)

Title	Application No. Application Date	(Publication No.) Patent No. Issue Date
High Power Transistor with Interior-Fed Fingers	17/834,421 7-Jun-2022	(2022/0302271)
Transistor Die Including Matching Circuit	17/900,652 31-Aug-2022	
Barrier Structure for Sub-100 Nanometer Gate Length Devices	17/951,711 23-Sep-2022	
Amplifier Output Impedance Control in Off Mode	18/061,246 02-Dec-2022	